

**Amendments to the Specification**

Please replace the paragraph beginning on page 29, line 14, with the following rewritten paragraph:

In addition, ~~as shown in Figs. 14B through 14D,~~ the power supply layer 11 and the ground layer 12 ~~may also be regarded~~will perform in the same manner as if they were as substantially overlapping when the power supply layer 11 and the ground layer 12 do not overlap but are contiguous when the circuit board is seen from above. For example, as shown in Figs. 14B through 14D, ~~when the power supply region 11 and the ground region 12 are adjacent on the same insulating board (the same layerplane).~~ and at least one inter-region of the power supply region 11 or the ground region 12 ~~these~~ has a shape that may be considered a track, ~~this~~ As discussed above, this ~~inter-region also can be treated the same~~will perform in the same manner as when the previous examples (where the power supply region 11 and the ground region 12 are formed in different layers with a dielectric interposed therebetween). The impedance  $Z_e$  in this case can be determined from the sectional configuration of the circuit board device in the direction orthogonal to the track direction by using a well known numerical calculation such as the finite element method or the like. In this case also, by disposing terminal loads 15 between the power supply layer region 11 and the ground ~~layer~~ region 12 at ends of portions of the track configuration of the ground layer, electromagnetic radiation noise can be reduced.